

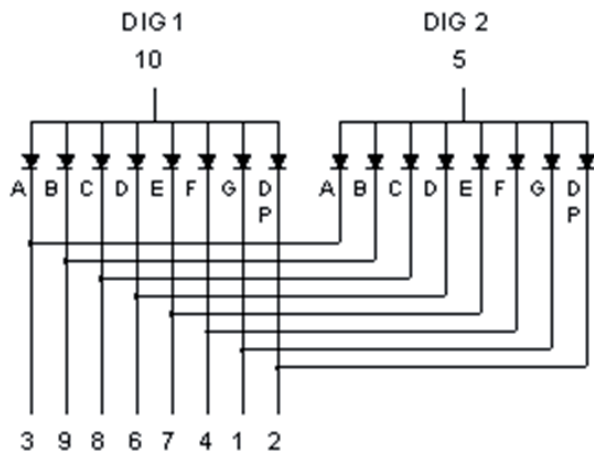
Pin Connection (Common Anode)

Pin No.	Connection
1	CATHODE G
2	CATHODE DP
3	CATHODE A
4	CATHODE F
5	COMMON ANODE DIG2
6	CATHODE D
7	CATHODE E
8	CATHODE C
9	CATHODE B
10	COMMON ANODE DIG1

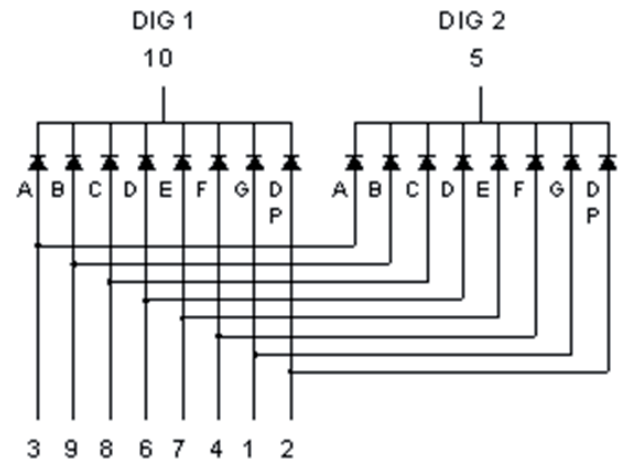
Pin Connection (Common Cathode)

Pin No.	Connection
1	ANODE G
2	ANODE DP
3	ANODE A
4	ANODE F
5	COMMON CATHODE DIG2
6	ANODE D
7	ANODE E
8	ANODE C
9	ANODE B
10	COMMON CATHODE DIG1

Internal Circuit Diagram (Common Anode)



Internal Circuit Diagram (Common Cathode)



Absolute Maximum Ratings @ $T_A=25^{\circ}\text{C}$

Parameter	Blue	Unit
Power Dissipation Per Segment	100	mW
Peak Forward Current Per Segment (1/10 Duty Cycle, 0.1ms pulse width)	80	mA
Continuous Forward Current Per Segment	25	mA
Derating Linearly From 25°C Per Segment	0.25	mA/°C
Reverse Voltage Per Segment	5	V
Operating Temperature Range		-40°C to+105°C
Storage Temperature Range		-40°C to+105°C

Caution in ESD: Static Electricity and surge damages the LED. It is recommend to use a wrist strap or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Electrical / Optical Characteristics @ $T_A=25^{\circ}\text{C}$

Blue

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Average Luminous Intensity	I_V	5.4	13.5	–	mcd	$I_F = 10 \text{ mA}$
Emission Wavelength	λ_p/λ_d	–	462/470	–	nm	$I_F = 20 \text{ mA}$
Spectral Line Half-Width	$\Delta\lambda$	–	26	–	nm	$I_F = 20 \text{ mA}$
Forward Voltage, Per Segment	V_F	–	3.3	4.0	V	$I_F = 20 \text{ mA}$
Reverse Current, Per Segment	I_R	–	–	100	μA	$V_R = 5 \text{ V}$
Luminous Intensity Matching Ratio	I_{V-m}	–	–	2:1	–	$I_F = 10 \text{ mA}$

Typical Electrical / Optical characteristic Curves @ $T_A=25^\circ\text{C}$
Blue

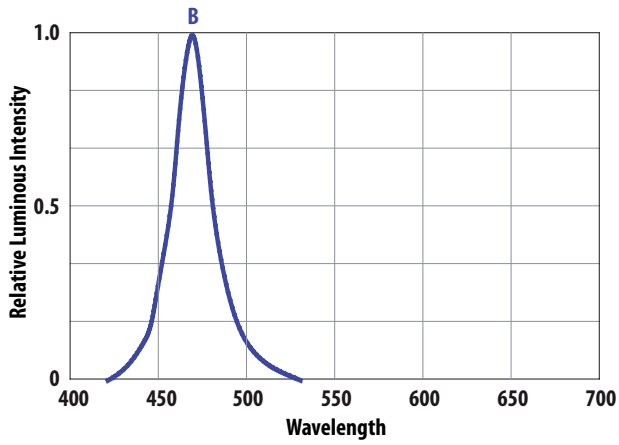


Figure 1. Relative Luminous Intensity vs. Wavelength

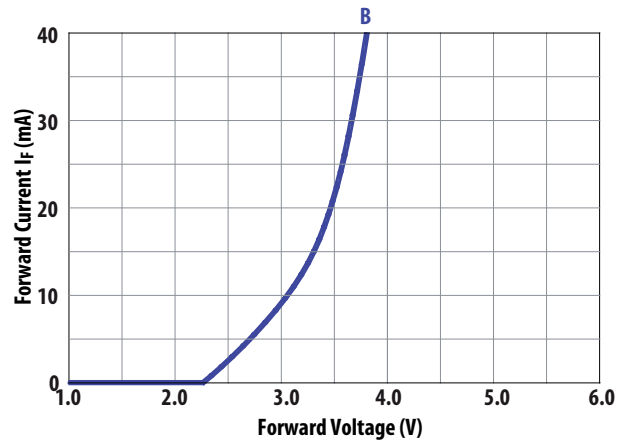


Figure 2. Forward Current vs. Forward Voltage

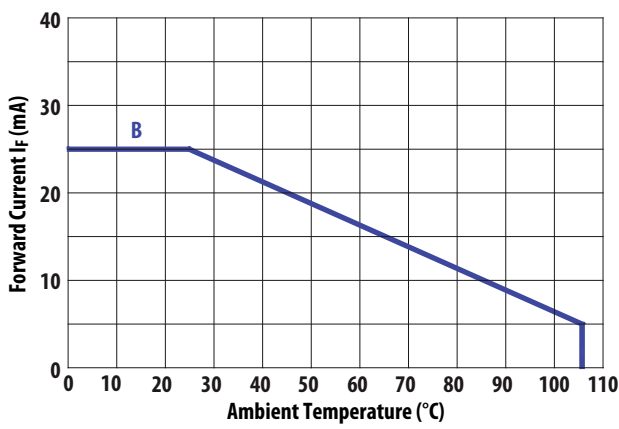


Figure 3. Allowable DC Current vs. Ambient Temperature

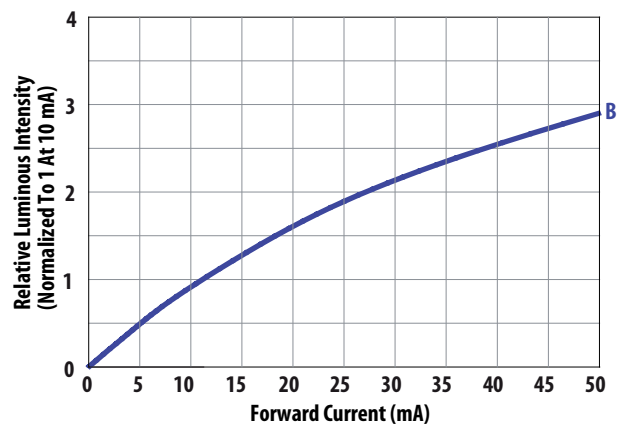


Figure 4. Relative Intensity vs. Forward Current

Intensity Bin Limit (mcd)

Blue

Iv Bin Category	Min	Max
M	5.401	8.600
N	8.601	13.700
P	13.701	21.800
Q	21.801	34.700

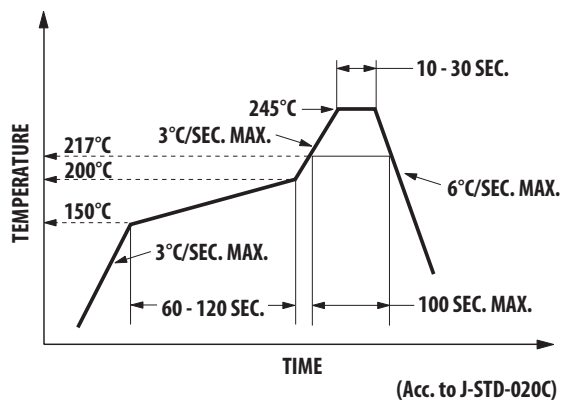
Tolerance +/-15%

Note:

1. Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Avago representative for information on currently available bins.

SMT Soldering Profile

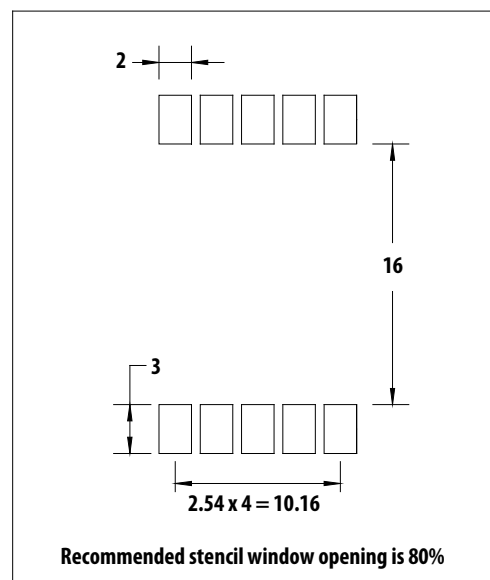
Pb free reflow soldering Profile



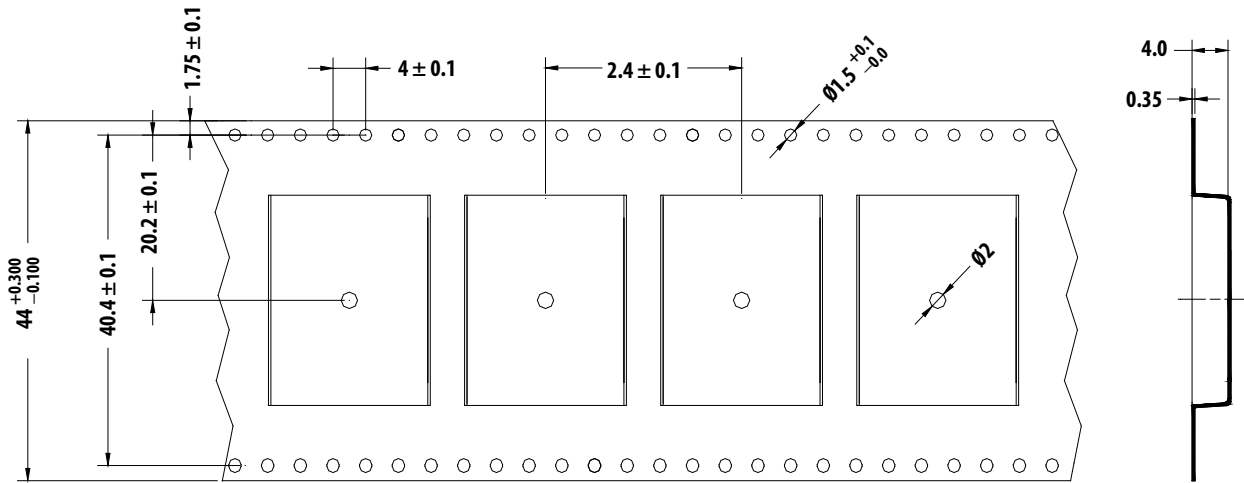
Notes:

1. The peak temperature refers to the peak package body temperature.
2. Number of reflow process shall be limited to maximum 2 times only. Cooling process to normal temperature is required between first and second soldering process.

Recommended Soldering Pattern (unit: mm)



Tape Specification (unit: mm)



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